



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			


Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-11-07
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Giovanni Giacopello	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.

Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
P6KE250CA	H2RH*TWB126G	A	ZA41	2016-11-07
Amount		UoM	Unit type	ST ECOPACK Grade
400.00		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
NAC	NAC	NAC		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
RAD	26 - 6.05 - 2.95	2	wire	
Comment	Package: DO 15			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	H2RH*TWB126G					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	4.014	mg	supplier	die	Silicon (Si)	7440-21-3		3.578	mg	891380	8945
				supplier	metallization	Aluminium (Al)	7429-90-5		0.384	mg	95665	960
				supplier	Passivation	Silicon Oxide	7631-86-9		0.032	mg	7972	80
				supplier	back side metallization	Aluminium (Al)	7429-90-5		0.007	mg	1745	18
				supplier	back side metallization	Gold (Au)	7440-57-5		0.002	mg	498	5
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.011	mg	2740	28
Leadframe	Copper & its alloys	280.420	mg	supplier	alloy	Copper (Cu)	7440-50-8		280.279	mg	999497	700698
				supplier	alloy	Zinc (Zn)	7440-66-6		0.028	mg	100	70
				supplier	alloy	Iron (Fe)	7439-89-6		0.028	mg	100	70
				supplier	alloy	Phosphorus (P)	12185-10-3		0.085	mg	303	213
Soft solder	Solder	4.773	mg	Supplier	soft solder	Silver (Ag)	7440-22-4		0.239	mg	50073	598
				Supplier	soft solder	Tin (Sn)	7440-31-5		0.119	mg	24932	298
				JIG R	soft solder	Lead (Pb)	7439-92-1	7a-Lead in high me	4.415	mg	924995	11034
Encapsulation	Other organic material	106.817	mg	Supplier	Molding Compound	silica fused	7631-86-9		42.727	mg	400002	106818
				Supplier	Molding Compound	silica quartz	14808-60-7		61.420	mg	575002	153550
				Supplier	Molding Compound	phenolic resin	9003-35-4		2.136	mg	19997	5340
				Supplier	Molding Compound	carbon black	1333-86-4		0.534	mg	4999	1335
Connections coating	Solder	3.976	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		3.976	mg	1000000	9940